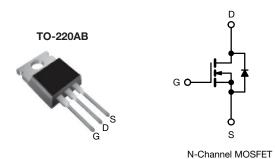
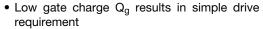


# **Power MOSFET**



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	400			
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = 10 V	1.0		
Q <sub>g</sub> max. (nC)	22			
Q <sub>gs</sub> (nC)	5.8			
Q <sub>gd</sub> (nC)	9.3			
Configuration	Single			

## **FEATURES**





Improved gate, avalanche and dynamic dV/dt ruggedness



- Fully characterized capacitance and avalanche voltage and current
- Effective C<sub>oss</sub> specified
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

### **APPLICATIONS**

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching

## **TYPICAL SMPS TOPOLOGIES**

- Single transistor flyback Xfmr. reset
- Single transistor forward Xfmr. reset (both US line input only)

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF730APbF		
Lead (Pb)-free and halogen-free	IRF730APbF-BE3		

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			$V_{DS}$	400	V	
Gate-source voltage			$V_{GS}$	± 30	7 v	
Continuous drain current	V -+ 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I <sub>D</sub>	5.5		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		3.5	Α	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	22		
Linear derating factor				0.6	W/°C	
Single pulse avalanche energy <sup>b</sup>			E <sub>AS</sub>	290	mJ	
Repetitive avalanche current a			I <sub>AR</sub>	5.5	А	
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	7.4	mJ	
Maximum power dissipation	T <sub>C</sub> =	25 °C	$P_{D}$	74	W	
Peak diode recovery dV/dt <sup>c</sup>			dV/dt	4.6	V/ns	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Soldering recommendations (peak temperature) <sup>d</sup>	For 10 s			300	7	
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

#### **Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Starting  $T_J = 25$  °C, L = 19 mH,  $R_g = 25 \Omega$ ,  $I_{AS} = 5.5$  A (see fig. 12)
- c.  $I_{SD} \le 5.5$  Å,  $dI/dt \le 90$  Å/µs,  $V_{DD} \le V_{DS}$ ,  $T_{J} \le 150$  °C
- d. 1.6 mm from case



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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R <sub>thJC</sub>	-	1.70			
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W		
Maximum junction-to-case (drain)	R <sub>thJA</sub>	-	62			

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		400	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.5	-	V/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> :	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.5	V
Gate-source leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 30 V		-	± 100	nA
		V <sub>DS</sub> :	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$		-	25	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 320 \	V <sub>DS</sub> = 320 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	250	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.3 A <sup>b</sup>	1	-	1.0	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 50 V, I <sub>D</sub> = 3.3 A	3.1	-	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$	-	600	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25 V, V <sub>DS</sub> = 25 V, f = 1.0 MHz, see fig. 5		-	103	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	4.0	-	
Output capacitance	C <sub>oss</sub>		V <sub>DS</sub> = 1.0 V, f = 1.0 MHz	1	890	-	pF -
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 320 V, f = 1.0 MHz	-	30	-	
Effective output capacitance	Coss eff.		V <sub>DS</sub> = 0 V to 320 V <sup>c</sup>	1	45	-	
Total gate charge	Qg			-	-	22	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 3.5 \text{ A}, V_{DS} = 320 \text{ V}$ see fig. 6 and 13 b		-	5.8	nC
Gate-drain charge	Q <sub>gd</sub>		See lig. 0 and 15	1	-	9.3	1
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD}$ = 200 V, $I_{D}$ = 3.5 A $R_{g}$ = 12 $\Omega$ , $R_{D}$ = 57 $\Omega$ , see fig. 10 b		-	10	-	- ns
Rise time	t <sub>r</sub>			-	22	-	
Turn-off delay time	t <sub>d(off)</sub>			1	20	-	
Fall time	t <sub>f</sub>			1	16	-	
Gate input resistance	Rg	f = 1 MHz, open drain		2.7	-	10.9	Ω
<b>Drain-Source Body Diode Characteristic</b>	cs						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	5.5	
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			-	-	22	A
Body diode voltage	V <sub>SD</sub>	$T_J = 25  ^{\circ}\text{C},  I_S = 5.5  \text{A},  V_{GS} = 0  \text{V}^{ \text{b}}$		-	-	1.6	V
Body diode reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = 3.5 A, dl/dt = 100 A/µs b		-	370	550	ns
Body diode reverse recovery charge	Q <sub>rr</sub>			-	1.6	2.4	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic to	ırn-on time is negligible (turn	on is dor	ninated b	v L <sub>s</sub> and	Ln)

## Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %
- c.  $C_{oss}$  eff. is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

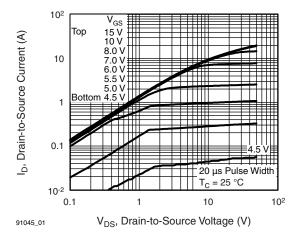


Fig. 1 - Typical Output Characteristics

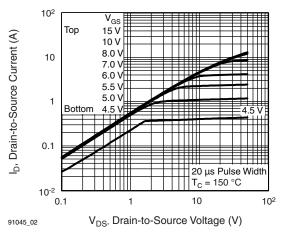


Fig. 2 - Typical Output Characteristics

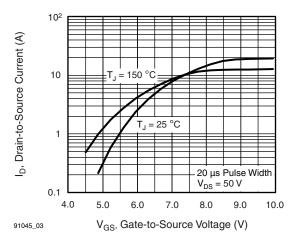


Fig. 3 - Typical Transfer Characteristics

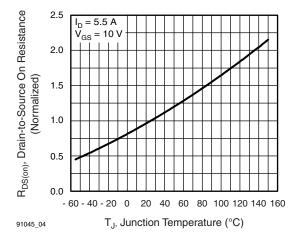


Fig. 4 - Normalized On-Resistance vs. Temperature

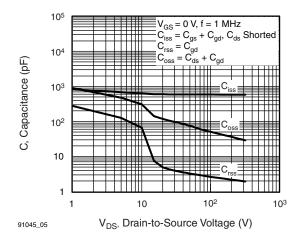


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

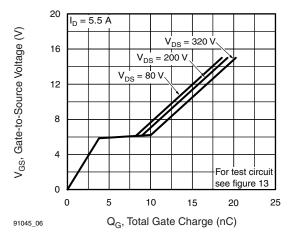


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



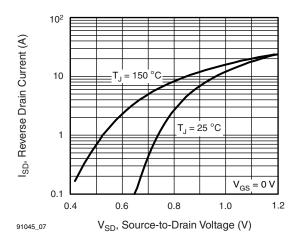


Fig. 7 - Typical Source-Drain Diode Forward Voltage

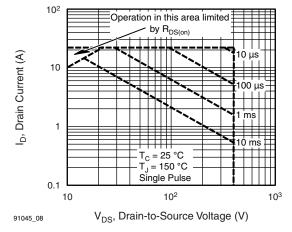


Fig. 8 - Maximum Safe Operating Area

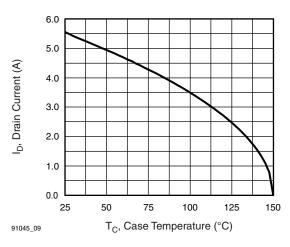


Fig. 9 - Maximum Drain Current vs. Case Temperature

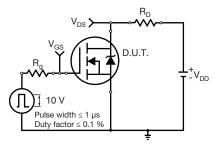


Fig. 10 - Switching Time Test Circuit

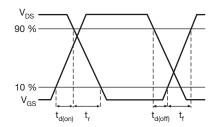
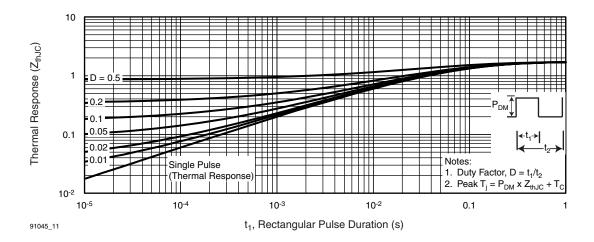


Fig. 11 - Switching Time Waveforms





## Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

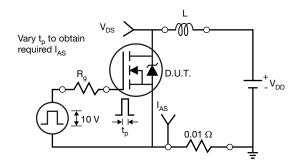


Fig. 13 - Unclamped Inductive Test Circuit

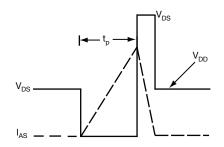


Fig. 14 - Unclamped Inductive Waveforms

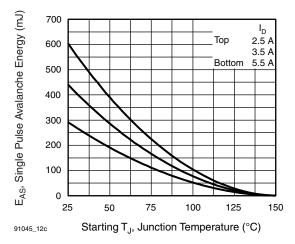


Fig. 15 - Maximum Avalanche Energy vs. Drain Current

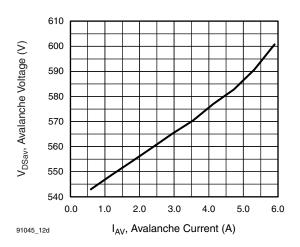


Fig. 16 - Typical Drain Source Voltage vs. Avalanche Current

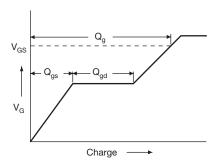


Fig. 17 - Basic Gate Charge Waveform

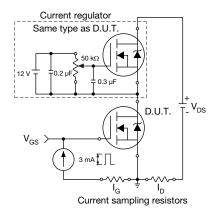
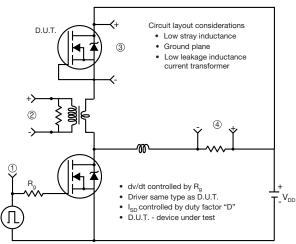


Fig. 18 - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



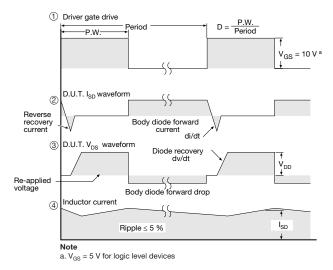


Fig. 19 - For N-Channel

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